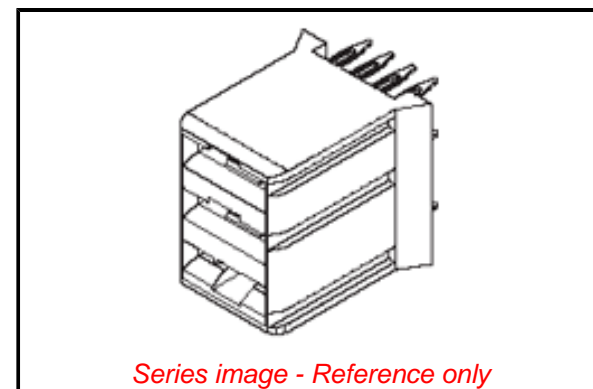


**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0736560001](#)  
**Status:** **Active**  
**Overview:** [HDM Backplane Connector System](#)  
**Description:** HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits

**Documents:**

<a href="#">3D Model</a>	<a href="#">Application Specification AS-73656-1998-001 (PDF)</a>
<a href="#">3D Model (PDF)</a>	<a href="#">Packaging Specification PK-70873-0819 (PDF)</a>
<a href="#">Drawing (PDF)</a>	<a href="#">RoHS Certificate of Compliance (PDF)</a>
<a href="#">Product Specification PS-73670-9999 (PDF)</a>	



**Agency Certification**

CSA	LR19980
UL	E29179

**General**

Product Family	Backplane Connectors
Series	<a href="#">73656</a>
Application	Backplane
Comments	Midplane Power Module, Molex Series 73659
Component Type	Power Header
Overview	<a href="#">HDM Backplane Connector System</a>
Product Name	HDM
UPC	800755024777

**Physical**

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	1.640/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.889µm
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55° to +105°C

**EU ELV**

**Not Relevant**

**EU RoHS**

**Compliant**

**REACH SVHC**

Not Contained Per -  
D(2020)4578-DC (25  
June 2020)

**Halogen-Free**

**Status**

**Low-Halogen**

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

Green Image

Not Relevant

Not Contained

**Search Parts in this Series**

[73656](#) Series

**Mates With**

[73651](#) HDM Board-to-Board Daughterboard Power Module

**Application Tooling | FAQ**

*Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.*

**Global**

Description	Product #
HDM Power Module	<a href="#">621001100</a>
Removal Tool	
Backplane Power	<a href="#">622005711</a>
Module Loading	
Heads	

Termination Interface: Style Through Hole - Compliant Pin

**Electrical**

Current - Maximum per Contact 15.0A  
Data Rate 1.0 Gbps  
Shielded No  
Voltage - Maximum 500V AC

**Solder Process Data**

Lead-freeProcess Capability N/A

**Material Info**

**Reference - Drawing Numbers**

Application Specification AS-73656-1998-001  
Packaging Specification PK-70873-0819  
Product Specification PS-73670-9999  
Sales Drawing SDA-73656-X00X-001

This document was generated on 07/16/2020

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